

LCD and Camera EMI Filter Array with ESD Protection

CM1452

Features

- Four, six and eight channels of EMI filtering with integrated ESD protection
- ±15kV ESD protection on each channel (IEC 61000-4-2 Level 4, contact discharge)
- ±30kV ESD protection on each channel (HBM)
- Greater than 30dB attenuation (typical) at 1 GHz
- Chip Scale Package (CSP) with 0.40mm pitch and 0.25mm CSP solder ball which features extremely low parasitic inductance for optimum filter and ESD performance
- OptiGuard[™] Coating for improved reliability at assembly
- RoHS-compliant, lead-free finishing

Applications

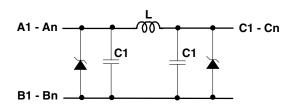
- LCD and Camera data lines in mobile handsets
- I/O port protection for mobile handsets, notebook computers, PDAs etc.
- EMI filtering for data ports in cell phones, PDAs or notebook computers.
- · Wireless handsets
- Handheld PCs/PDAs
- LCD and camera modules

Product Description

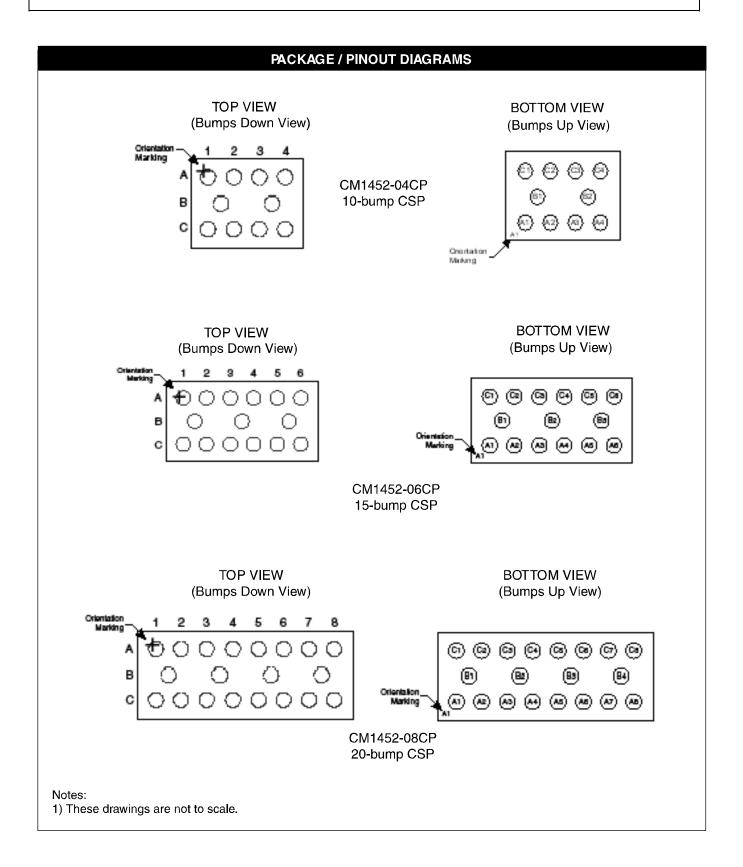
The CM1452 family of pi-style EMI filter arrays with ESD protection, integrates four, six and eight filters (C-L-C) in CSP form factor with 0.40mm pitch. Each EMI filter channel of the CM1452 is implemented as a 3-pole L-C filter where the component values are 20pF-17nH-20pF. The CM1452 roll-off frequency at -6dB attenuation is 330MHz and can be used in applications where the data rates are as high as 132Mbps and provide greater than 30dB over the 800MHz to 2.7GHz frequency range. The ESD diodes on every I/O pin provide a very high level of ESD protection for sensitive electronic components. The ESD protection diodes connected to the filter ports are designed and characterized to safely dissipate ESD strikes of ±15kV, beyond the maximum requirement of the IEC61000-4-2 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges at greater than ±30kV.

The CM1452 incorporates *OptiGuard*[™] which results in improved reliability at assembly. The CM1452 is manufactured with a 0.40mm pitch and 0.25mm CSP solder ball to provide up to 28% board space savings vs. competing CSP devices with 0.50mm pitch and 0.30mm CSP solder ball.

Electrical Schematic



CM1452 schematic diagram of 3-pole L-C filter array with ESD.



Pin Descriptions

	PIN DESCRIPTIONS											
PIN NUMBER		R	PIN		PIN NUMBE	R	PIN					
-04	-06	-08	DESCRIPTION	-04	-06	-08	DESCRIPTION					
A1	A1	A1	Filter #1	C1	C1	C1	Filter #1					
A2	A2	A2	Filter #2	C2	C2	C2	Filter #2					
А3	АЗ	A3	Filter #3	СЗ	СЗ	СЗ	Filter #3					
A4	A4	A4	Filter #4	C4	C4	C4	Filter #4					
	A5	A5	Filter #5		C5	C5	Filter #5					
	A6	A6	Filter #6		C6	C6	Filter #6					
		A7	Filter #7			C7	Filter #7					
		A8	Filter #8			C8	Filter #8					
B1	B1	B1	GND									
B2	B2	B2	GND									
	В3	В3	GND									
		B4	GND									

Ordering Information

PART NUMBERING INFORMATION									
	Lead-free Finish								
# of Channels	Leads	Package	Ordering Part Number ¹	Part Marking					
4	10	CSP	CM1452-04CP	52					
6	15	CSP	CM1452-06CP	L526					
8	20	CSP	CM1452-08CP	L528					

Note 1: Parts are shipped in Tape and Reel form unless otherwise specified.

CM1452

Specifications

ABSOLUTE MAXIMUM RATINGS								
PARAMETER	RATING	UNITS						
Operating Temperature Range	-40 to +85	°C						
Storage Temperature Range	-65 to +150	°C						

STANDARD OPERATING CONDITIONS								
PARAMETER	RATING	UNITS						
Operating Temperature Range	-40 to +85	°C						

	ELECTRICAL OPER	RATING CHARACTERIS	TICS (SEE NO	TE 1)		
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
L _{CHAN}	Channel Inductance			17		nH
С _{тот}	Total Channel Capacitance at 2.5Vdc; 1MHz, 30mVac	2.5V dc; 1MHz, 30mV ac	24	30	36	pF
C ₁	Capacitance C1 at 2.5V dc; 1MHz, 30mV ac	2.5V dc; 1MHz, 30mV ac		15		pF
f _c	Cut-off Frequency, ZSOURCE = 50Ω , ZLOAD = 50Ω			148		MHz
f _R	Roll-off Frequency at -6dB Attenuation, ZSOURCE = 50Ω , ZLOAD = 50Ω			330		MHz
V _{st}	Stand-off Voltage, I = 10mA		5.5			V
I _{LEAK}	Diode Leakage at 3.3V reverse bias voltage			0.1	1.0	μА
V _{SIG}	Signal Clamp Voltage: Positive Clamp Negative Clamp	$I_{LOAD} = 10mA$ $I_{LOAD} = -10mA$	5.6 -1.5	6.8 -0.8	9.0 -0.4	V V
V _{ESD}	In-system ESD withstand voltage*: a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2 Level 4	Notes 2 and 3	±30 ±15			kV kV
R _{DYN}	Dynamic Resistance Channel Positive Transients Channel Negative Transients			2.3 0.9		ΩΩ
A _L	Current per Inductor:	_			30	mA
DC	DC Package Power Rating:				30	W

Note 1: All parameters specified at $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ unless otherwise noted.

Note 2: ESD applied to input/output pins with respect to GND, one at a time. Clamping voltage is measured at the opposite side of the EMI filter to the ESD pin (i.e. if ESD is applied to pin A1 then clamping voltage is measured at pin C1).

Note 3: Unused pins are left open.

Performance Information

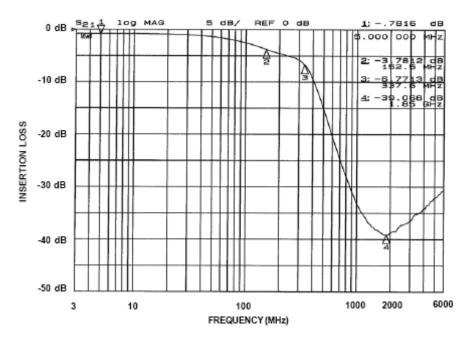


Figure 1. Insertional Loss vs. Frequency (Filter 1: CM1452-04, -06, -08)

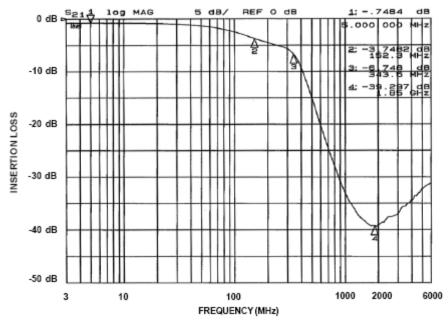


Figure 2. Insertional Loss vs. Frequency (Filter 2: CM1452-04, -06, -08)

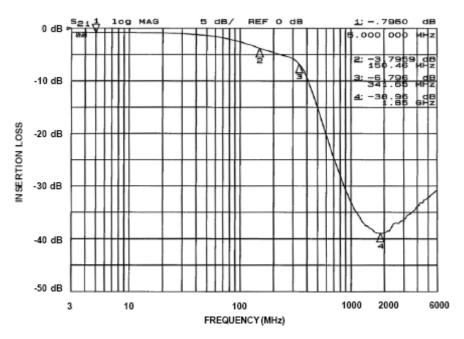


Figure 3. Insertional Loss vs. Frequency (Filter 3: CM1452-04, -06, -08)

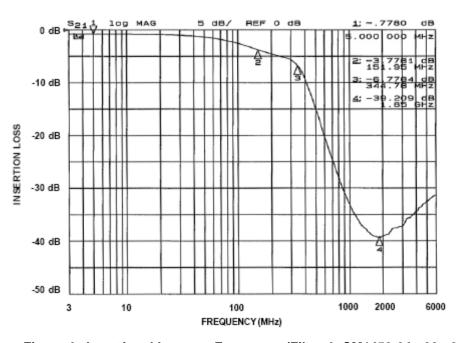


Figure 4. Insertional Loss vs. Frequency (Filter 4: CM1452-04, -06, -08)

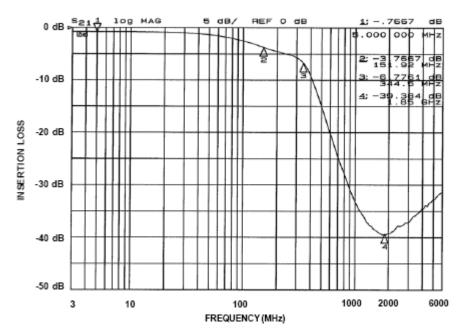


Figure 5. Insertional Loss vs. Frequency (Filter 5: CM1452-06, -08)

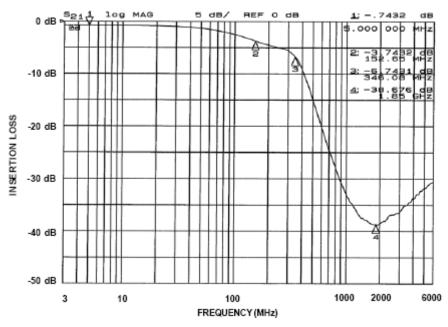


Figure 6. Insertional Loss vs. Frequency (Filter 6: CM1452-06, -08)

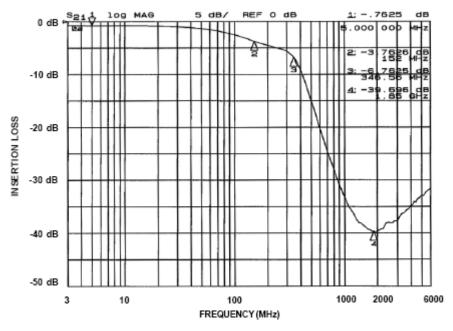


Figure 7. Insertional Loss vs. Frequency (Filter 7: CM1452-08)

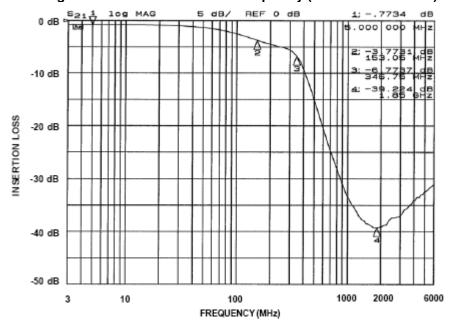


Figure 8. Insertional Loss vs. Frequency (Filter 8: CM1452-08)

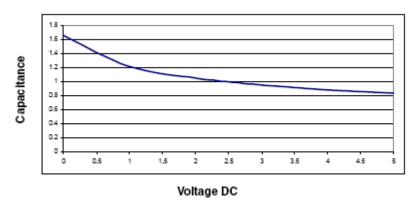


Figure 9. CM1452 Typical Diode Capacitance vs. Input Voltage (Normalized to 2.5Vdc)

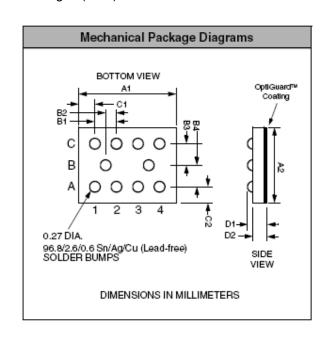
Application Information

Refer to Application Note AP-217, "The Chip Scale Package", for a detailed description of Chip Scale Packages offered by California Micro Devices. See http://www.wlcspforum.org/documents/pdf/ap-217.pdf for download.

Mechanical Specifications

CM1452-04CP devices are packaged in custom Chip Scale Packages (CSP).

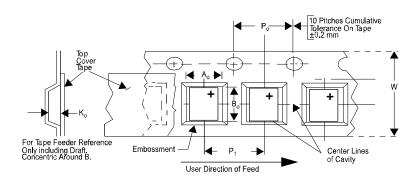
	PACKAGE DIMENSIONS									
Pack	age		Custom CSP							
Burr	nps			10						
Dim	М	illimete	rs		Inches					
	Min	Nom	Max	Min	Nom	Max				
A 1	1.627	1.672	1.717	0.0641	0.0658	0.0676				
A 2	1.068	1.113	1.158	0.0420	0.0438	0.0456				
B1	0.395	0.400	0.405	0.0156	0.0157	0.0159				
B2	0.195	0.200	0.205	0.0077	0.0079	0.0081				
В3	0.342	0.347	0.352	0.0135	0.0137	0.0139				
B4	0.342	0.347	0.352	0.0135	0.0137	0.0139				
C1	0.186	0.236	0.286	0.0073	0.0093	0.0113				
C2	0.160	0.210	0.260	0.0063	0.0082	0.0102				
D1	0.545	0.615	0.685	0.0215	0.0242	0.0270				
D2	0.378	0.419	0.460	0.0149	0.0165	0.0181				
# per tape and reel		3500 pieces								
	Controlling dimension: millimeters									



Package Dimensions for CM1452-04CP Chip Scale Package

CSP Tape and Reel Specifications

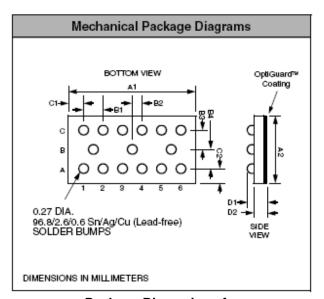
PART NUMBER	CHIP SIZE (mm)	POCKET SIZE (mm) B _o X A _o X K _o	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P _o	P ₁
CM1452-04CP	1.67 X 1.11 X 0.615	1.73 X 1.23 X 0.83	8mm	178mm (7")	3500	4mm	4mm



Mechanical Specifications

CM1452-06CP devices are packaged in custom Chip Scale Packages (CSP).

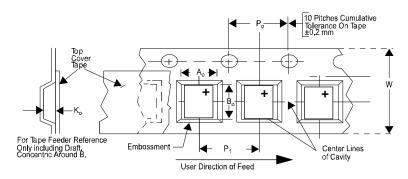
	PACKAGE DIMENSIONS									
Pack	age		(Custom C	SP					
Burr	nps			15						
Dim	M	illimete	rs		Inches					
	Min	Nom	Max	Min	Nom	Max				
A 1	2.427	2.472	2.517	0.0956	0.0973	0.0991				
A2	1.068	1.113	1.158	0.0420	0.0438	0.0456				
B1	0.395	0.400	0.405	0.0156	0.0157	0.0159				
B2	0.195	0.200	0.205	0.0077	0.0079	0.0081				
В3	0.342	0.347	0.352	0.0135	0.0137	0.0139				
B4	0.342	0.347	0.352	0.0135	0.0137	0.0139				
C1	0.186	0.236	0.286	0.0073	0.0093	0.0113				
C2	0.160	0.210	0.260	0.0063	0.0082	0.0102				
D1	0.545	0.615	0.685	0.0215	0.0242	0.0270				
D2	0.368	0.419	0.470	0.0145	0.0165	0.0185				
# per tape and reel		3500 pieces								
	Con	trolling o	dimensio	on: millim	eters					



Package Dimensions for CM1452-06CP Chip Scale Package

CSP Tape and Reel Specifications

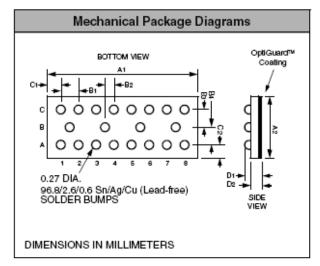
PART NUMBER	CHIP SIZE (mm)	POCKET SIZE (mm) B _o X A _o X K _o	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P _o	P ₁
CM1452-06	2.47 X 1.11X 0.615	2.59 X 1.27 X 0.73	8mm	178mm (7")	3500	4mm	4mm



Mechanical Specifications

CM1452-08CP devices are packaged in custom Chip Scale Packages (CSP).

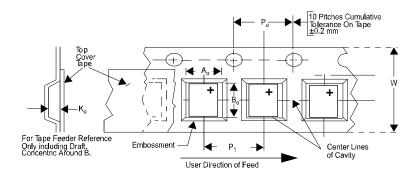
	PACKAGE DIMENSIONS									
Pack	age		(Custom C	SP					
Burr	nps			20						
Dim	M	illimete	ers		Inches					
	Min	Nom	Max	Min	Nom	Max				
A 1	3.227	3.272	3.317	0.1270	0.1288	0.1306				
A2	1.068	1.113	1.158	0.0420	0.0438	0.0456				
B1	0.395	0.400	0.405	0.0156	0.0157	0.0159				
B2	0.195	0.200	0.205	0.0077	0.0079	0.0081				
В3	0.342	0.347	0.352	0.0135	0.0137	0.0139				
B4	0.342	0.347	0.352	0.0135	0.0137	0.0139				
C1	0.186	0.236	0.286	0.0073	0.0093	0.0113				
C2	0.160	0.210	0.260	0.0063	0.0082	0.0102				
D1	0.545	0.615	0.685	0.0215	0.0242	0.0270				
D2	0.368	0.419	0.470	0.0145	0.0165	0.0185				
# per tape and reel		3500 pieces								
Controlling dimension: millime				eters						



Package Dimensions for CM1452-08CP Chip Scale Package

CSP Tape and Reel Specifications

PART NUMBER	CHIP SIZE (mm)	POCKET SIZE (mm) B _o X A _o X K _o	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P _o	P,
CM1452-08CP	3.27 X 1.11X 0.615	3.40 X 1.19 X 0.74	12mm	330mm (13")	3500	4mm	4mm



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